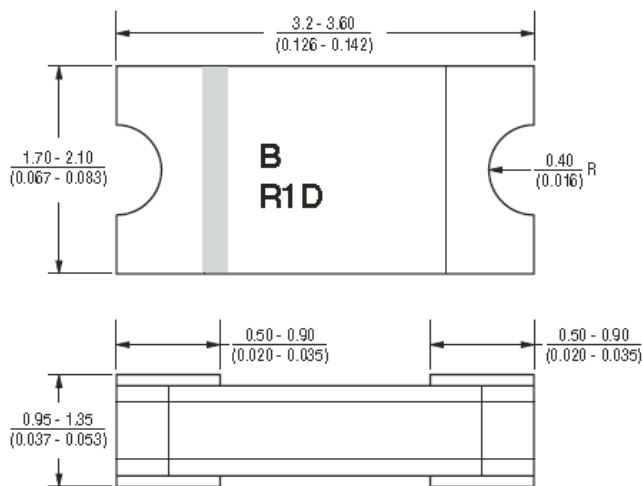


Product Dimensions

This is a lead free product, packaged with FRP substrate and is epoxy underfilled. The terminals are pure tin plated and are solderable per MIL-STD-750, Method 2026. The package weighs approximately 0.02 g. The package and dimensions are shown below.



Recommended Footprint

The device will mount onto existing JEDEC SOD-87 footprint.

How To Order

	CD 1408 - R 1 400
Common Code	_____
CD = Chip Diode	_____
Package	_____
1408 = ~0.14 x 0.08"	_____
Function	_____
R = Rectifier	_____
Forward Current $I_{(AV)}$	_____
1 = 1 A	_____
Reverse Voltage	_____
200 = 200 V	_____
400 = 400 V	_____
600 = 600 V	_____
800 = 800 V	_____
1000 = 1000 V	_____

Typical Part Marking

CD1408-R1200	R1D
CD1408-R1400	R1G
CD1408-R1600	R1J
CD1408-R1800	R1K
CD1408-R11000	R1M